

May 8, 2006

Data Sheet

12-Channel TFT-LCD Reference Voltage Generator with External Shutdown

The EL5325A with external shutdown is designed to produce the reference voltages required in TFT-LCD applications. Each output is programmed to the required voltage with 10 bits of resolution. Reference pins determine the high and low voltages of the output range, which are capable of swinging to either supply rail. Programming of each output is performed using the 3-wire, SPI compatible interface.

A number of EL5325A can be stacked for applications requiring more than 12 outputs. The reference inputs can be tied to the rails, enabling each part to output the full voltage range, or alternatively, they can be connected to external resistors to split the output range and enable finer resolutions of the outputs.

The EL5325A has 12 outputs and is available in a 28 Ld TSSOP package. They are specified for operation over the full -40 $^{\circ}$ C to +85 $^{\circ}$ C temperature range.

PART NUMBER	PART MARKING	TAPE & REEL	PACKAGE	PKG. DWG. #	
EL5325AIREZ (Note)	5325AIREZ	-	28 Ld HTSSOP (Pb-Free)	MDP0048	
EL5325AIREZ-T7 (Note)	5325AIREZ	7"	28 Ld HTSSOP (Pb-Free)	MDP0048	
EL5325AIREZ-T13 (Note)	5325AIREZ	13"	28 Ld HTSSOP (Pb-Free)	MDP0048	
EL5325AIRZ (Note)	5325AIRZ	-	28 Ld TSSOP (Pb-Free)	MDP0044	
EL5325AIRZ-T7 (Note)	5325AIRZ	7"	28 Ld TSSOP (Pb-Free)	MDP0044	
EL5325AIRZ-T13 (Note)	5325AIRZ	13"	28 Ld TSSOP (Pb-Free)	MDP0044	

Ordering Information

NOTE: Intersil Pb-free plus anneal products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate termination finish, which are RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

Features

- 12-channel reference outputs
- Accuracy of ±1%
- Supply voltage of 5V to 16.5V
- Digital supply 3.3V to 5V
- Low supply current of 10mA
- Rail-to-rail capability
- Internal thermal protection
- External shutdown
- Pb-free plus anneal available (RoHS compliant)

Applications

- TFT-LCD drive circuits
- Reference voltage generators

Pinout

(28 L	EL5325A D TSSOP/HTS TOP VIEW	SOP)
ENA 1		28 OUTA
SDI 2		27 ООТВ
SCLK 3		26 OUTC
SDO 4		25 GND
EXT_OSC 5		24 OUTD
VS 6		23 OUTE
SHDN 7		22 OUTF
VSD 8		21 OUTG
REFH 9		20 ООТН
REFL 10		19 OUTI
VS 11		18 GND
GND 12		17 OUTJ
CAP 13		16 OUTK
NC 14		15 OUTL

Absolute Maximum Ratings $(T_A = 25 \degree)$

Supply Voltage between V _S & GND4.5V (min) to 18V (max)
Supply Voltage between V_{SD} & GND . 3V (min) to V_S and 7V (max)
Maximum Continuous Output Current
Power Dissipation See Curves

 Maximum Die Temperature
 +125℃

 Storage Temperature
 -65℃ to +150℃

 Ambient Operating Temperature
 -40℃ to +85℃

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

IMPORTANT NOTE: All parameters having Min/Max specifications are guaranteed. Typ values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore: $T_J = T_C = T_A$

Electrical Specifications $V_S = 15V$, $V_{SD} = 5V$, $V_{REFH} = 13V$, $V_{REFL} = 2V$, $R_L = 1.5k\Omega$ and $C_L = 200pF$ to 0V, $T_A = 25^{\circ}C$, unless otherwise specified.

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY	1		1			
IS	Supply Current	No load		10.2	12.5	mA
I _{SD}	Digital Supply Current			0.17	0.35	mA
ANALOG	1					
V _{OL}	Output Swing Low	Sinking 5mA ($V_{REFH} = 15V, V_{REFL} = 0$)		50	150	mV
V _{OH}	Output Swing High	Sourcing 5mA ($V_{REFH} = 15V, V_{REFL} = 0$)	14.85	14.95		V
I _{SC}	Short Circuit Current	$R_L = 10\Omega$	100	140		mA
PSRR	Power Supply Rejection Ratio	V _S + is moved from 14V to 16V	45	65		dB
t _D	Program to Out Delay			4		ms
V _{AC}	Accuracy referred to the ideal value	Code = 512		20		mV
ΔV_{MIS}	Channel to Channel Mismatch	Code = 512		2		mV
V _{DROOP}	Droop Voltage			1	2	mV/ms
R _{INH}	Input Resistance @ V _{REFH} , V _{REFL}			32		kΩ
REG	Load Regulation	I _{OUT} = 5mA step		0.5	1.5	mV/mA
CAP	Band Gap	By pass with 0.1µF	1	1.3	1.6	V
DIGITAL	1					
V _{IH}	Logic 1 Input Voltage	$V_{SD} = 5V$	4			V
		V _{SD} = 3.3V	2			V
F _{CLK}	Clock Frequency				5	MHz
V _{IL}	Logic 0 Input Voltage	$V_{SD} = 3.3 V/5 V$			1	V
t _S	Setup Time			20		ns
t _H	Hold Time			20		ns
^t LC	Load to Clock Time			20		ns
^t CE	Clock to Load Line			20		ns
t _{DCO}	Clock to Out Delay Time	Negative edge of SCLK		10		ns
R _{SDIN}	S _{DIN} Input Resistance			1		GΩ
T _{PULSE}	Minimum Pulse Width for EXT_OSC Signal			5		μs
Duty Cycle	Duty Cycle for EXT_OSC Signal			50		%
INL	Integral Nonlinearity Error			1.3		LSB
DNL	Differential Nonlinearity Error			0.5		LSB
F_OSC	Internal Refresh Oscillator Frequency	OSC_Select = 0		21		kHz
V _{IH_SHDN}	SHDN Voltage Input High		2			V
IIH_SHDN	SHDN Current Input High	SHDN = 2V		100		μA

Pin Descriptions

EL5325A	PIN NAME	PIN TYPE	PIN FUNCTION					
1	ENA	Logic Input	Chip select, low enables data input to logic					
2	SDI	Logic Input	Serial data input					
3	SCLK	Logic Input	Serial data clock					
4	SDO	Logic Output	Serial data output					
5	EXT_OSC	Logic Input/Output	External oscillator input or internal oscillator output					
6, 11	VS+	Analog Power	Positive supply voltage for analog circuits					
7	SHDN	Logic Input	Chip shutdown: float enables chip, high > 2V disables chip					
8	VSD	Digital Power	Positive power supply for digital circuits (3.3V - 5V)					
9	REFH	Analog Reference Input	High reference voltage					
10	REFL	Analog Reference Input	Low reference voltage					
12	GND	Ground	Ground					
13	CAP	Analog Bypass Pin	Decoupling capacitor for internal reference generator, 0.1µF					
14	NC		Not connected					
17	OUTJ	Analog Output	Channel J programmable output voltage					
19	OUTI	Analog Output	Channel I programmable output voltage					
20	OUTH	Analog Output	Channel H programmable output voltage					
21	OUTG	Analog Output	Channel G programmable output voltage					
22	OUTF	Analog Output	Channel F programmable output voltage					
23	OUTE	Analog Output	Channel E programmable output voltage					
24	OUTD	Analog Output	Channel D programmable output voltage					
26	OUTC	Analog Output	Channel C programmable output voltage					
27	OUTB	Analog Output	Channel B programmable output voltage					
28	OUTA	Analog Output	Channel A programmable output voltage					
15	OUTL	Analog Output	Channel L programmable output voltage					
16	OUTK	Analog Output	Channel K programmable output voltage					
18, 25	GND	Power	Ground					

Typical Performance Curves

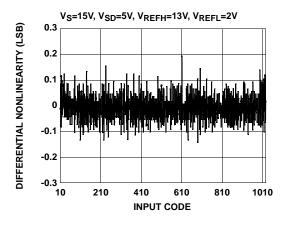


FIGURE 1. DIFFERENTIAL NONLINEARITY vs CODE

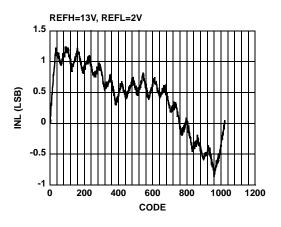


FIGURE 2. INTEGRAL NONLINEARITY ERROR

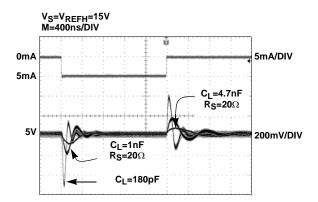


FIGURE 3. TRANSIENT LOAD REGULATION (SOURCING)

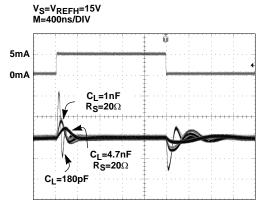


FIGURE 4. TRANSIENT LOAD REGULATION (SINKING)

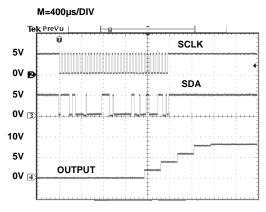
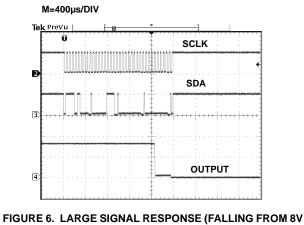
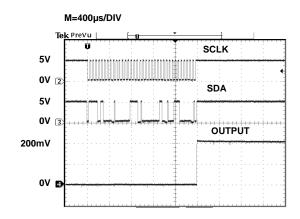


FIGURE 5. LARGE SIGNAL RESPONSE (RISING FROM 0V TO 8V)





Typical Performance Curves (Continued)



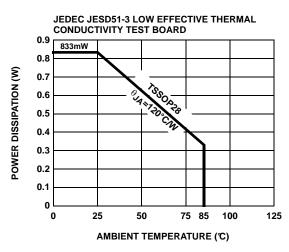
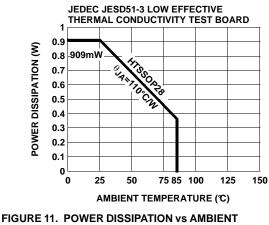


FIGURE 9. POWER DISSIPATION vs AMBIENT TEMPERATURE



TEMPERATURE

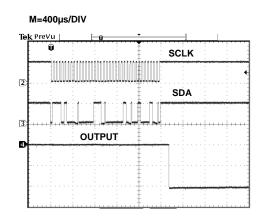
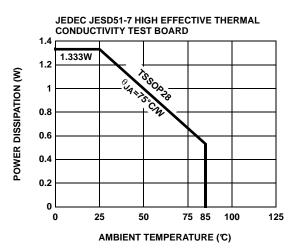


FIGURE 8. SMALL SIGNAL RESPONSE (FALLING FROM 200mV TO 0V)





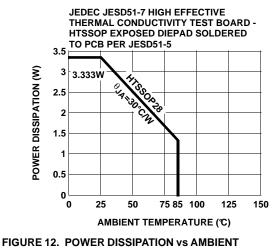


FIGURE 12. POWER DISSIPATION VS AMBIEN TEMPERATURE

General Description

The EL5325A provides a versatile method of providing the reference voltages that are used in setting the transfer characteristics of LCD display panels. The V/T (Voltage/Transmission) curve of the LCD panel requires that a correction is applied to make it linear; however, if the panel is to be used in more than one application, the final curve may differ for different applications. By using the EL5325A, the V/T curve can be changed to optimize its characteristics according to the required application of the display product. Each of the eight reference voltage outputs can be set with a 10-bit resolution. These outputs can be driven to within 50mV of the power rails of the EL5325A. As all of the output buffers are identical, it is also possible to use the EL5325A for applications other than LCDs where multiple voltage references are required that can be set to 10 bit accuracy.

Digital Interface

The EL5325A uses a simple 3-wire SPI compliant digital interface to program the outputs. The EL5325A can support the clock rate up to 5MHz.

Serial Interface

The EL5325A is programmed through a three-wire serial interface. The start and stop conditions are defined by the $\overline{\text{ENA}}$ signal. While the $\overline{\text{ENA}}$ is low, the data on the SDI (serial data input) pin is shifted into the 16-bit shift register on the positive edge of the SCLK (serial clock) signal. The MSB (bit 15) is loaded first and the LSB (bit 0) is loaded last (see Table 1). After the full 16-bit data has been loaded, the $\overline{\text{ENA}}$ is pulled high and the addressed output channel is updated. The SCLK is disabled internally when the $\overline{\text{ENA}}$ is high. The SCLK must be low before the $\overline{\text{ENA}}$ is pulled low.

To facilitate the system designs that use multiple EL5325A chips, a buffered serial output of the shift register (SDO pin) is available. Data appears on the SDO pin at the 16th falling SCLK edge after being applied to the SDI pin.

To control the multiple EL5325A chips from a single threewire serial port, just connect the ENA pins and the SCLK pins together, connect the SDO pin to the SDI pin on the next chip. While the ENA is held low, the 16m-bit data is loaded to the SDI input of the first chip. The first 16-bit data will go to the last chip and the last 16-bit data will go to the first chip. While the ENA is held high, all addressed outputs will be updated simultaneously.

The Serial Timing Diagram and parameters table show the timing requirements for three-wire signals.

The serial data has a minimum length of 16 bits, the MSB (most significant bit) is the first bit in the signal. The bits are

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allocated to the following functions (also refer to the Control Bits Logic Table)

- Bit 15 is always set to a zero
- Bit 14 controls the sourceof the clock, see the next section for details
- Bits 13 through 10 select the channel to be written to, these are binary coded with channel A = 0, and channel H = 7
- The 10-bit data is on bits 9 through 0. Some examples of data words are shown in the table of Serial Programming Examples

BIT	NAME	DESCRIPTION					
B15	Test	Always 0					
B14	Oscillator	0 = Internal, 1 = External					
B13	A3	Channel Address					
B12	A2	Channel Address					
B11	A1	Channel Address					
B10	A0	Channel Address					
B9	D9	Data					
B8	D8	Data					
B7	D7	Data					
B6	D6	Data					
B5	D5	Data					
B4	D4	Data					
B3	D3	Data					
B2	D2	Data					
B1	D1	Data					
B0	D0	Data					

TABLE 1. CONTROL BITS LOGIC TABLE

Serial Timing Diagram

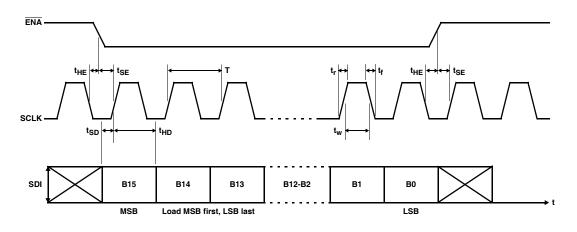
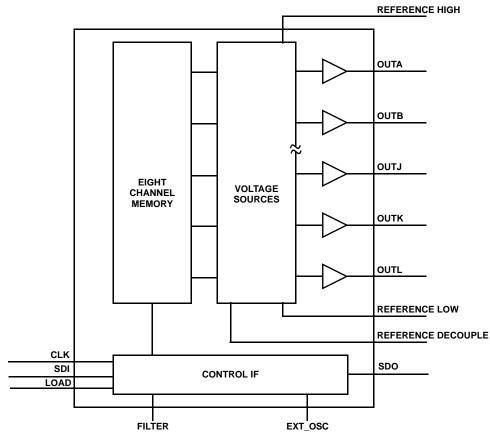


TABLE 2. SERIAL TIMING PARAMETERS

PARAMETER	RECOMMENDED OPERATING RANGE	DESCRIPTION			
Т	≥200ns	Clock Period			
t _r /t _f	0.05 * T	Clock Rise/Fall Time			
t _{HE}	≥10ns	ENA Hold Time			
tSE	≥10ns	ENA Setup Time			
t _{HD}	≥10ns	Data Hold Time			
t _{SD}	≥10ns	Data Setup Time			
t _W	0.50 * T	Clock Pulse Width			

CON	TROL	СНА	NNEL	ADDF	RESS					DA	TA	CONDITION					
C1	C0	A3	A2	A1	A0	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0	CONDITION	
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	Internal Oscillator, Channel A, Value = 0	
0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	Internal Oscillator, Channel A, Value = 1023	
0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	Internal Oscillator, Channel A, Value = 512	
0	0	0	0	1	1	1	0	0	0	0	0	0	0	0	1't	Internal Oscillator, Channel C, Value = 513	
0	0	0	1	1	1	0	0	0	0	0	1	1	1	1	1	Internal Oscillator, Channel H, Value = 31	
0	1	0	1	1	1	0	0	0	0	0	1	1	1	1	1	External Oscillator, Channel H, Value = 31	

Block Diagram



Analog Section

TRANSFER FUNCTION

The transfer function is:

$$V_{OUT(IDEAL)} = V_{REFL} + \frac{data}{1024} \times (V_{REFH} - V_{REFL})$$

where data is the decimal value of the 10-bit data binary input code.

The output voltages from the EL5325A will be derived from the reference voltages present at the V_{REFL} and V_{REFH} pins. The impedance between those two pins is about 32k Ω .

Care should be taken that the system design holds these two reference voltages within the limits of the power rails of the EL5325A. GND < V_{REFH} \leq V_S and GND \leq V_{REFL} \leq V_{REFH}.

In some LCD applications that require more than 12 channels, the system can be designed such that one EL5325A will provide the Gamma correction voltages that are more positive than the V_{COM} potential. The second EL5325A can provide the Gamma correction voltage more negative than the V_{COM} potential. The Application Drawing shows a system connected in this way.

CLOCK OSCILLATOR

The EL5325A requires an internal clock or external clock to refresh its outputs. The outputs are refreshed at the falling OSC clock edges. The output refreshed switches open at the rising edges of the OSC clock. The driving load shouldn't be changed at the rising edges of the OSC clock. Otherwise, it will generate a voltage error at the outputs. This clock may be input or output via the clock pin labeled OSC. The internal clock is provided by an internal oscillator running at approximately 21kHz and can be output to the OSC pin. In a 2 chip system, if the driving loads are stable, one chip may be programmed to use the internal oscillator; then the OSC pin will output the clock from the internal oscillator. The second chip may have the OSC pin connected to this clock source.

For transient load application, the external clock Mode should be used to ensure all functions are synchronized together. The positive edge of the external clock to the OSC pin should be timed to avoid the transient load effect. The Application Drawing shows the LCD H rate signal used, here the positive clock edge is timed to avoid the transient load of the column driver circuits.

After power on, the chip will start with the internal oscillator mode. At this time, the OSC pin will be in a high impedance condition to prevent contention. By setting B14 to high, the

chip is on external clock mode. Setting B14 to low, the chip is on internal clock mode.

CHANNEL OUTPUTS

Each of the channel outputs has a rail-to-rail buffer. This enables all channels to have the capability to drive to within 50mV of the power rails, (see Electrical Characteristics for details).

When driving large capacitive loads, a series resistor should be placed in series with the output. (Usually between 5Ω and 50Ω).

Each of the channels is updated on a continuous cycle, the time for the new data to appear at a specific output will depend on the exact timing relationship of the incoming data to this cycle.

The best-case scenario is when the data has just been captured and then passed on to the output stage immediately; this can be as short as $48\mu s$. In the worst-case scenario this will be 576 μs when the data has just missed the cycle.

When a large change in output voltage is required, the change will occur in 2V steps, thus the requisite number of timing cycles will be added to the overall update time. This means that a large change of 16V can take between 4.6ms to 5.2ms depending on the absolute timing relative to the update cycle.

POWER DISSIPATION AND THERMAL SHUTDOWN

With the 30mA maximum continues output drive capability for each channel, it is possible to exceed the 125°C absolute maximum junction temperature. Therefore, it is important to calculate the maximum junction temperature for the application to determine if load conditions need to be modified for the part to remain in the safe operation.

The maximum power dissipation allowed in a package is determined according to:

$$\mathsf{P}_{\mathsf{DMAX}} = \frac{\mathsf{T}_{\mathsf{JMAX}} - \mathsf{T}_{\mathsf{AMAX}}}{\Theta_{\mathsf{JA}}}$$

where:

- TJMAX = Maximum junction temperature
- T_{AMAX} = Maximum ambient temperature
- θ_{JA} = Thermal resistance of the package
- PDMAX = Maximum power dissipation in the package

The maximum power dissipation actually produced by the IC is the total quiescent supply current times the total power supply voltage and plus the power in the IC due to the loads.

$$\mathsf{P}_{\mathsf{DMAX}} = \mathsf{V}_{\mathsf{S}} \times \mathsf{I}_{\mathsf{S}} + \Sigma[(\mathsf{V}_{\mathsf{S}} - \mathsf{V}_{\mathsf{OUT}}\mathsf{i}) \times \mathsf{I}_{\mathsf{LOAD}}\mathsf{i}]$$

when sourcing, and:

$$\mathbf{P}_{\mathbf{DMAX}} = \mathbf{V}_{\mathbf{S}} \times \mathbf{I}_{\mathbf{S}} + \Sigma(\mathbf{V}_{\mathbf{OUT}}\mathbf{i} \times \mathbf{I}_{\mathbf{LOAD}}\mathbf{i})$$

when sinking.

Where:

- i = 1 to total 12
- V₅ = Supply voltage
- Vouti = Output voltage of the i channel
- LOADi = Load current of the i channel

By setting the two P_{DMAX} equations equal to each other, we can solve for the R_{LOAD} s to avoid the device overheat. The package power dissipation curves provide a convenient way to see if the device will overheat.

The EL5325A has an internal thermal shutdown circuitry that prevents overheating of the part. When the junction temperature goes up to about 150°C, the part will be disabled. When the junction temperature drops down to about 120°C, the part will be ena bled. With this feature, any short circuit at the outputs will enable the thermal shutdown circuitry to disable the part.

POWER SUPPLY BYPASSING AND PRINTED CIRCUIT BOARD LAYOUT

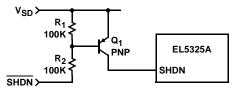
Good printed circuit board layout is necessary for optimum performance. A low impedance and clean analog ground plane should be used for the EL5325A. The traces from the two ground pins to the ground plane must be very short. The thermal pad of the EL5325A should be connected to the analog ground plane. Lead length should be as short as possible and all power supply pins must be well bypassed. A 0.1μ F ceramic capacitor must be place very close to the V_S, V_{REFH}, V_{REFL}, and CAP pins. A 4.7μ F local bypass tantalum capacitor should be placed to the V_S, V_{REFH}, and V_{REFL} pins.

APPLICATION USING THE EL5325A

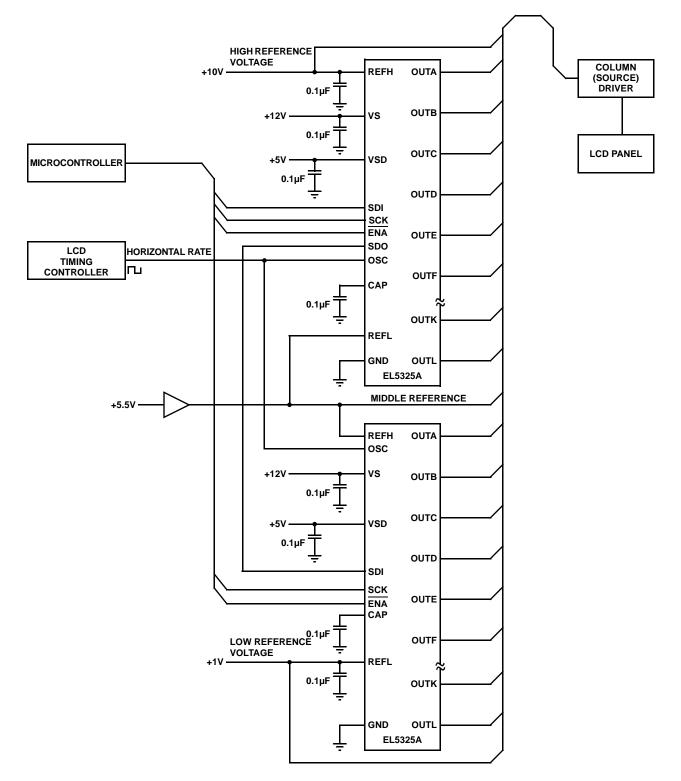
In the first application drawing, the schematic shows the interconnect of a pair of EL5325A chips connected to give 12 gamma corrected voltages above the V_{COM} voltage, and 12 gamma corrected voltages below the V_{COM} voltage.

External Shutdown

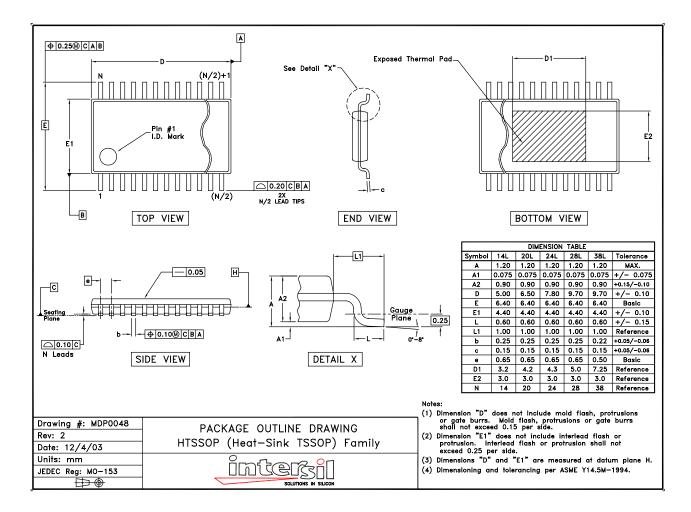
The EL5325A also has an external shutdown to enable and disable the part. The SHDN pin should never be driven low. Rather, to enable the part, the SHDN pin must be left open (float). To disable, the SHDN pin must be driven HI (>2V). WIth this feature, the EL5325A can be forced to shut down, regardless of any other conditions. A simple open collector driver is adequate to control the enable and disable function:



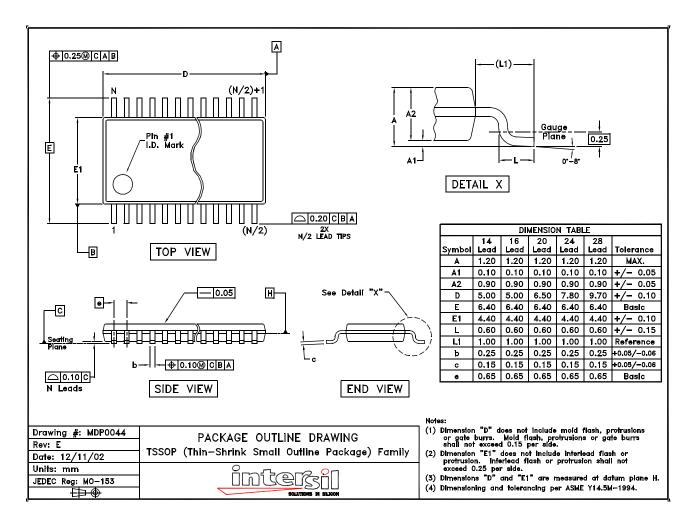
Application Drawing



Package Outline Drawing (HTSSOP)



TSSOP Package Outline Drawing



NOTE: The package drawing shown here may not be the latest version. To check the latest revision, please refer to the Intersil website at http://www.intersil.com/design/packages/index.asp

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